

IN THE SPECIFICATION

Insert new paragraph on page 9, between lines 18 and 19 (between existing paragraphs):

As is shown in Fig. 2A, the conductive pattern 26 has a first width near to the posts 16, underlaying redistribution wiring layer 14 and conducting parts of the chip 10, and a greater second width near to the conductive layer 24, the second width being wider than the first width.